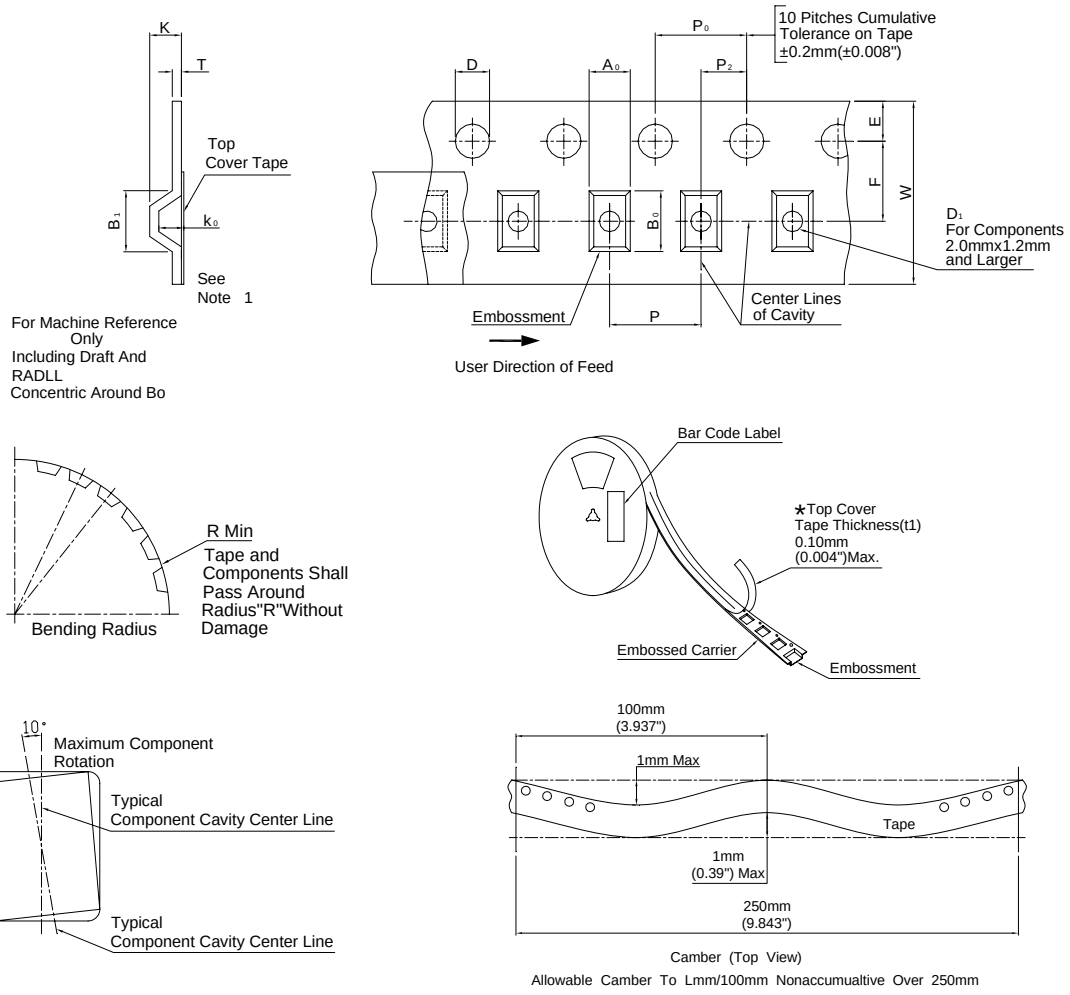
Embossed Tape and Reel Data for Surface Mounted Mold Diodes Carrier Tape Specifications



Dimensions

Tape Size	B1 Max.	D	D1	E	F	K	P0	P2	R Min.	T Max.	W Max.
8 mm	4.55mm (0.179")	1.5 +0.1mm -0.0	1.0 Min (0.039")	1.75± 0.1 mm (0.069± 0.004)	3.5 ± 0.05 mm (0.138 ± 0.002")	2.4 mm Max (0.094")	4 ± 0.1 mm (0.157 ± 0.004")	2 ± 0.1 mm (0.079 ± 0.002")	25 mm (0.98")	0.6 mm (0.024")	8.3 mm (0.327")
12 mm	8.2mm (0.323")	(0.059 + 0.004"-0.0)	1.5 mm Min (0.060")	-	5.5 ± 0.05 mm (0.217 ± 0.002")	6.4 mm Max (0.252")	-	-	30 mm (1.18")	-	12 ± 0.30 mm (0.47±0.012")
16 mm	12.1mm (0.476")	-	-	-	7.5 ± 0.10 mm (0.295 ± 0.004")	7.9 mm Max (0.311")	-	-	-	-	16.3 mm (0.642")
24 mm	20.1mm (0.791")	-	-	-	11.5 ± 0.10 mm (0.453 ± 0.004")	11.9 mm Max (0.468")	-	-	-	-	24.3 mm (0.957")

Metric dimensions govern-English are in parentheses for reference only.

Note 1: A_0, B_0, and K_0 are determined by component size. The clearance between the components and the cavity must be within 0.05 mm min. to 0.5 mm max. The component cannot rotate more than 10^o within the determined cavity.

Note 2: If B_1 exceeds 4.2 mm(0.165") for 8 mm embossed tape, the tape may not feed through all tape feeders.